

VERSION WITH MARKINGS TO SHOW CHANGES MADE**IN THE SPECIFICATION:**

The paragraph on page 12, lines 9-19, has been amended as follows:

The above-described first embodiment of the present invention has the following meritorious effects. FIG. 7 schematically shows the effect of the first embodiment of the present invention. Referring to FIG. 7, heat 13 evolved from an active element is radiated not only from the source electrode 4 but also from the drain electrode 3 via the electrically conductive member 6 and the aluminum nitride 5 exhibiting high thermal conductivity. Thus, the heat 13 evolved from the active element is radiated via two channels to improve the thermal dissipation efficiency higher than [that] is possible with the conventional device.

Claim 3 has been amended as follows:

3. (Twice Amended) A semiconductor device wherein a first terminal of an [the] active element is connected via a thermally and [an] electrically conductive member to a heat sink member, and [wherein] a second terminal of the active element transmits heat to said heat sink member via at least a thermally conductive electrically [an] insulating member interposed in between said second terminal of the active element and the heat sink member such that a void is formed between said thermally and electrically conductive member and said thermally conductive electrically insulating member.

Claim 10 has been amended as follows:

10. (Twice Amended) A semiconductor device as defined in claim 21 wherein said thermally conductive electrically insulating member is arranged on at least one of (a) a

terminal surface of said active element and [/or] (b) a surface of said heat sink member [side of the package] used for mounting the active element.

Claim 21 has been amended as follows:

21. (Twice Amended) A semiconductor device comprising:
a heat sink member having a thermally and electrically conductive protrusion formed thereon;
an active element having a plurality of terminals; and
a thermally conductive electrically [an] insulating member formed of a single insulating layer on the active element and connecting one of the [first or second] plurality of terminals of said active element to the heat sink member, [the other of the first and second terminals] said thermally and electrically conductive protrusion connecting another one of said plurality of terminals of said active element to the heat sink member [via the protrusion].